
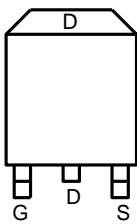


# TM150N12T

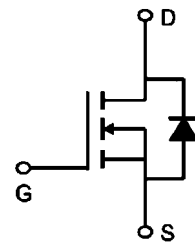
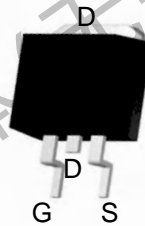
## N-Channel Enhancement Mosfet

<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low R<sub>DS(ON)</sub></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p>V<sub>DS</sub> = 120V I<sub>D</sub> = 150A</p> <p>R<sub>DS(ON)</sub> = 4.3 mΩ (typ.) @ V<sub>GS</sub> = 10V</p> <p>100% UIS Tested 100% R<sub>g</sub> Tested</p> 
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T:TO-263-3L



Marking: 150N12



### Absolute Maximum Ratings (T<sub>C</sub> = 25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	120	V
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	150	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	95	A
I <sub>DM</sub>	Pulsed Drain Current	1050	A
EAS	Single Pulse Avalanche Energy	304	mJ
I <sub>AS</sub>	Avalanche Current	36	A
P <sub>D</sub>	Total Power Dissipation	156	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient	---	---	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case	---	0.8	°C/W



**TM150N12T**

**N-Channel Enhancement Mosfet**

Electrical Characteristics: ( $T_C=25^\circ\text{C}$  unless otherwise noted)

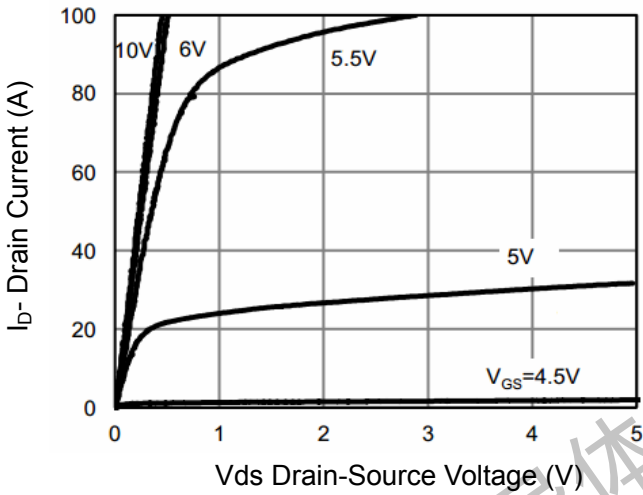
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	120	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	2.5	3.0	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	4.3	5.5	$\text{m}\Omega$
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$	-	12148	-	pF
$C_{oss}$	Output Capacitance		-	518	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	441	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 50\text{V}, I_D = 15\text{A}$	-	230	-	nC
$Q_{gs}$	Gate Source Charge		-	56	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	76	-	nC
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$ $I_D = 30\text{A}, R_{GEN} = 6\Omega$	-	40	-	ns
$t_r$	Turn-On Rise Time		-	68	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	99	-	ns
$t_f$	Turn-Off Fall Time		-	91	-	ns
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		--	--	150	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1050	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	-	113	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	274	-	nC



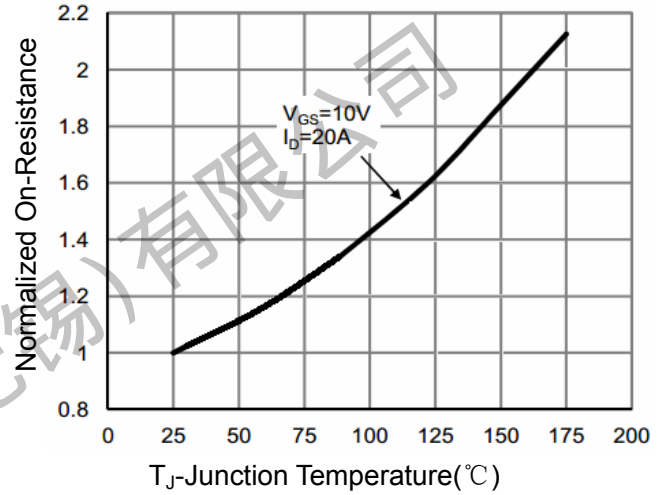
**TM150N12T**

**N-Channel Enhancement Mosfet**

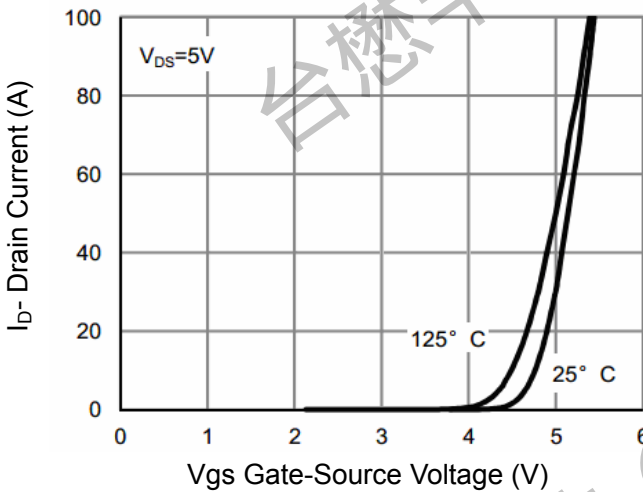
**Typical Electrical and Thermal Characteristics (Curves**



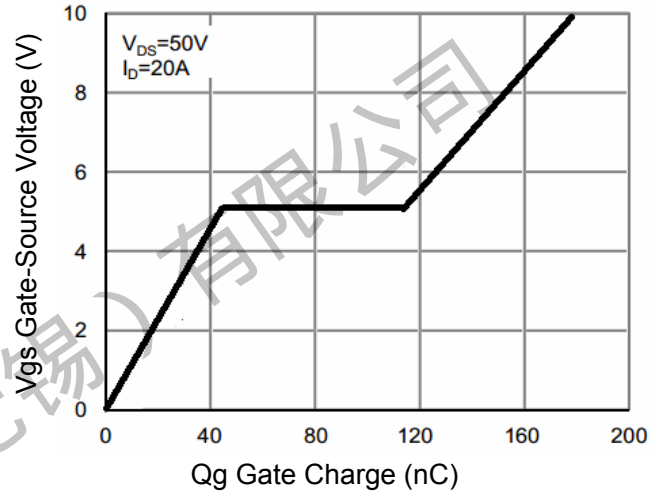
**Figure 1 Output Characteristics**



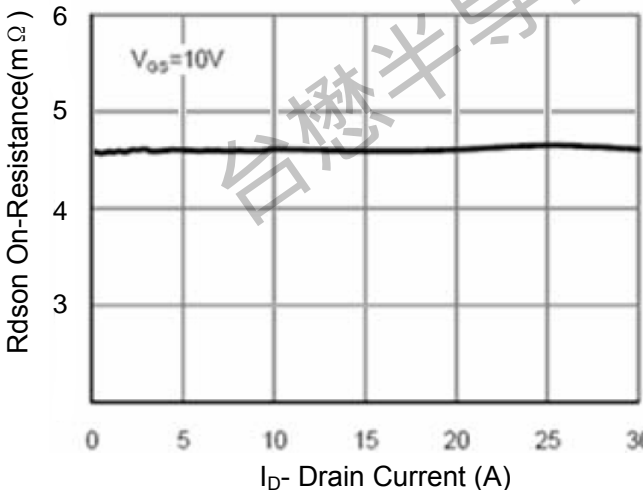
**Figure 4 Rdson-Junction Temperature**



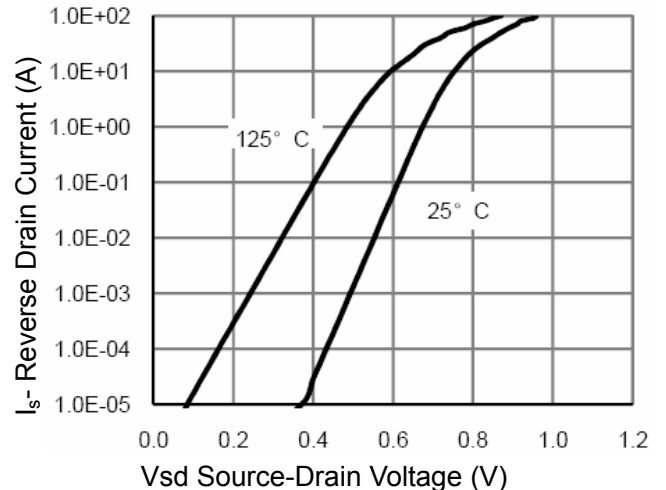
**Figure 2 Transfer Characteristics**



**Figure 5 Gate Charge**



**Figure 3 Rdson- Drain Current**

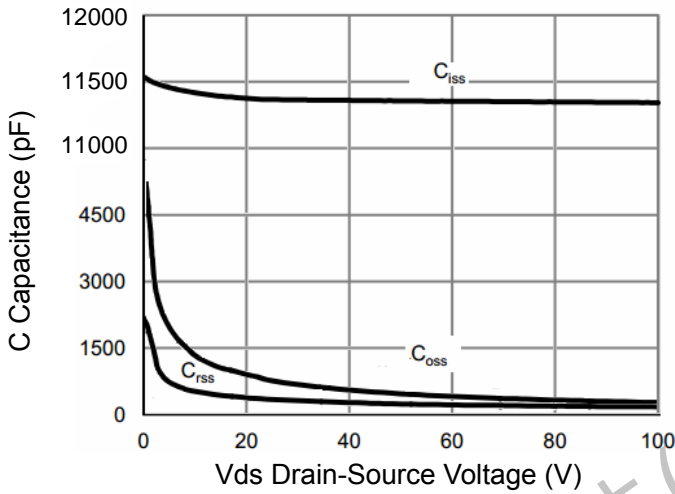


**Figure 6 Source- Drain Diode Forward**

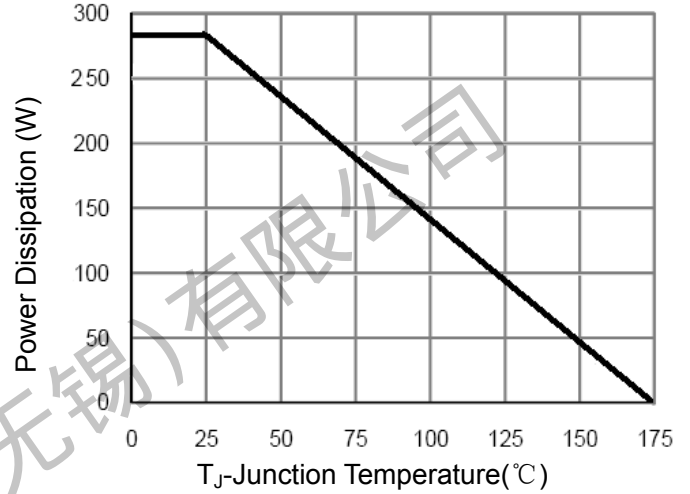


**TM150N12T**

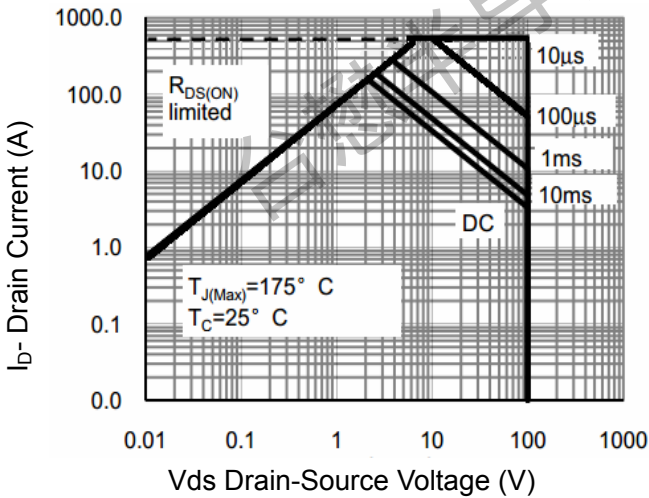
**N-Channel Enhancement Mosfet**



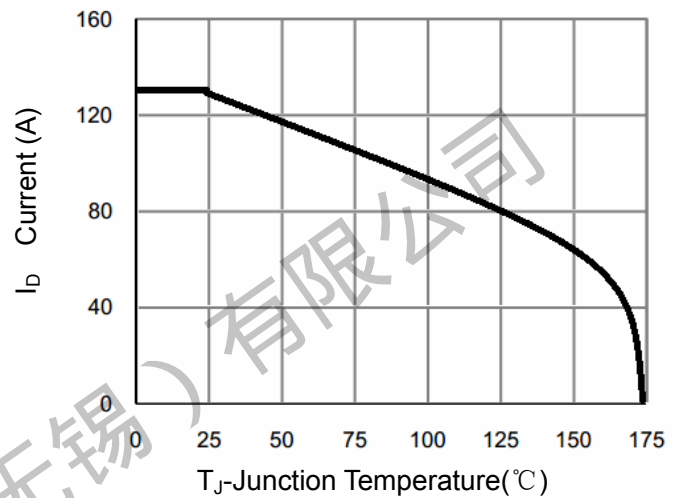
**Figure 7 Capacitance vs Vds**



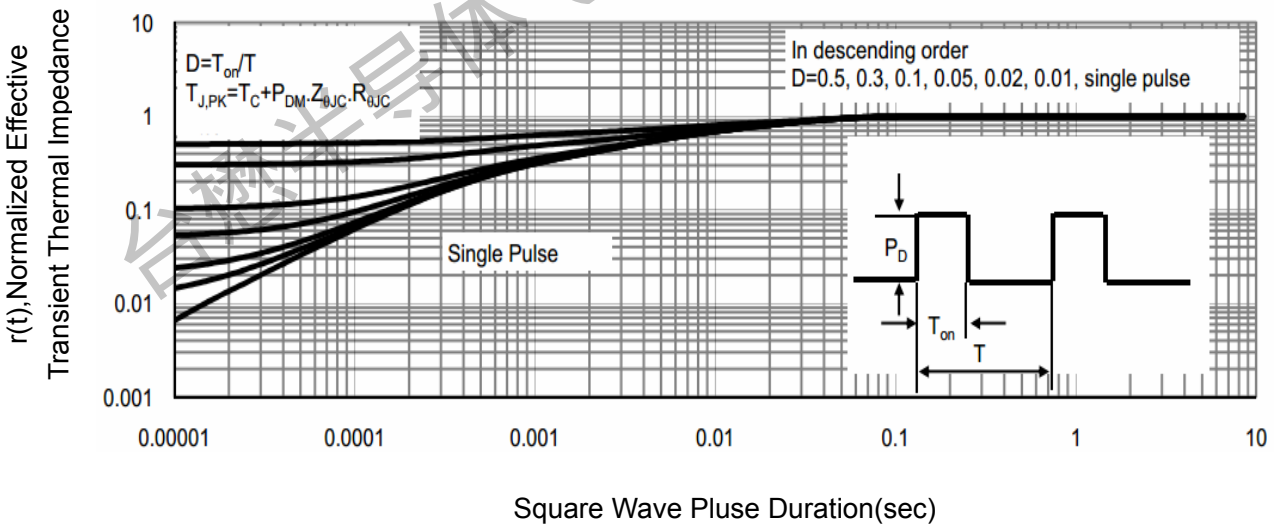
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**



**Figure 10 ID Current- Junction Temperature**

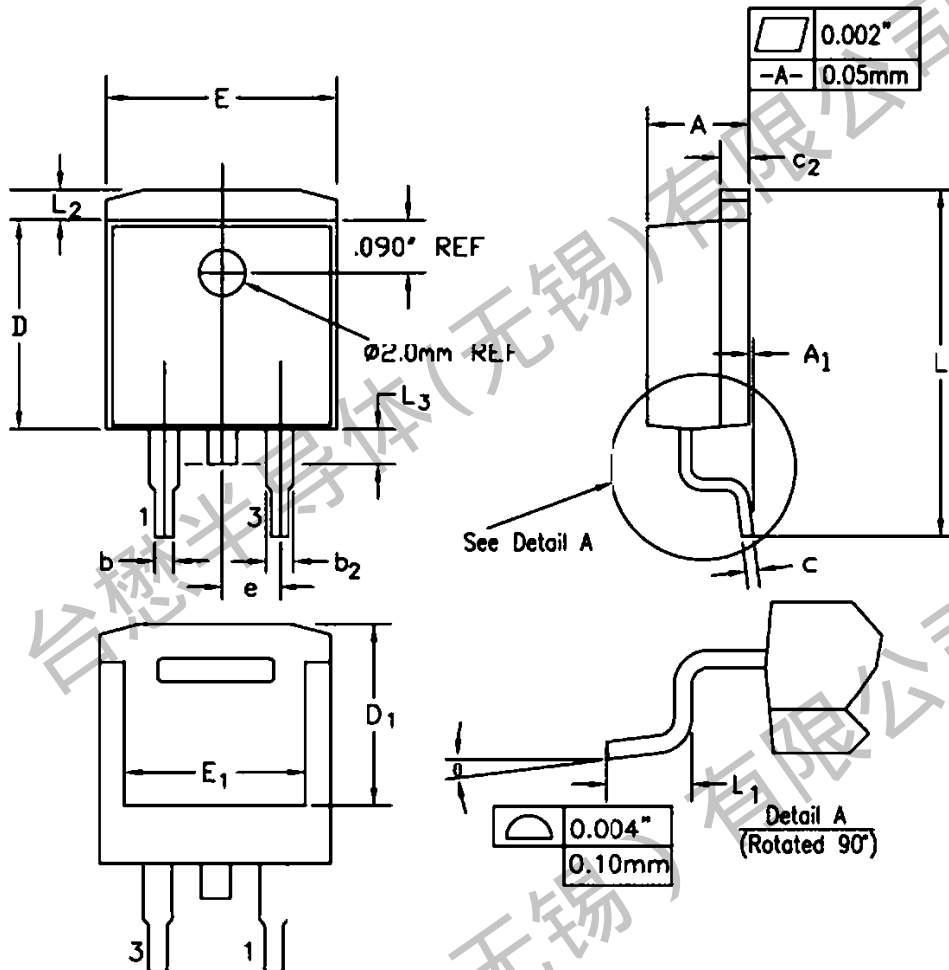


**Figure 11 Normalized Maximum Transient Thermal Impedance**

TM150N12T

N-Channel Enhancement Mosfet

Package Mechanical Data: TO-263-3L



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	
A1	-	0.010	-	0.25	
b	0.028	0.037	0.71	0.94	
b2	0.045	0.055	1.15	1.40	
c	0.018	0.024	0.46	0.61	
c2	0.048	0.055	1.22	1.40	
D	0.350	0.370	8.89	9.40	
D1	0.315	0.324	8.01	8.23	
E	0.395	0.405	10.04	10.28	
E1	0.310	0.318	7.88	8.08	
e	0.100 BSC.		2.54 BSC.		
L	0.580	0.620	14.73	15.75	
L1	0.090	0.110	2.29	2.79	
L2	0.045	0.055	1.15	1.39	
L3	0.050	0.070	1.27	1.77	
θ	0°	8°	0°	8°	

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Revision history:

Date	Rev	Description	Page
2023.12.11	23.12	Original	